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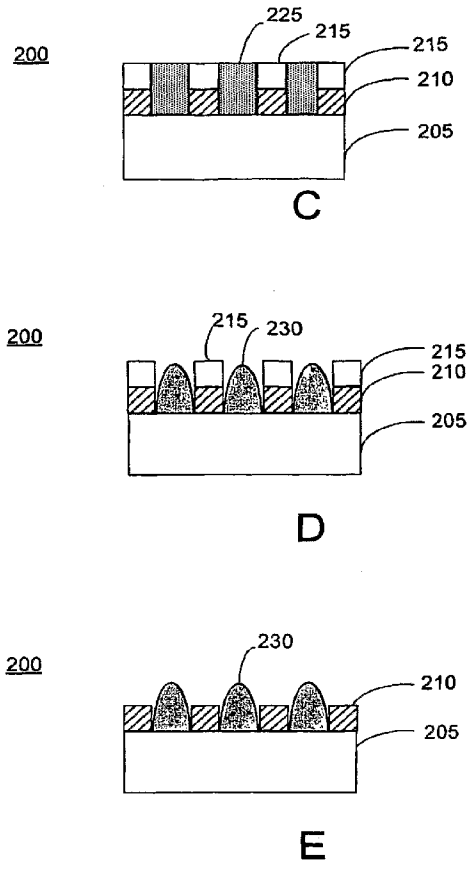
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(54) Title: METHOD FOR ADVANCED SOLDER BUMPING AND SYSTEM MANUFACTURED BY SAID METHOD



(57) Abstract: According to some embodiments, a method, apparatus, and system are provided. In some embodiments, the method includes providing solder resist material on a surface of a substrate, applying mask material on top of the solder resist material, reflowing solder located in an opening formed through both the solder resist material and the mask material, and removing the mask material after the reflowing of the solder.

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